

### **Addition of Abstract**

Please add the following abstract to the patent application, this abstract being taken directly from the PCT application and modified to conform to U.S. practice.

A method for gluing microcomponents to a substrate (1) during the production of microsystem components includes the steps of applying a reactive or non-reactive hot melt type adhesive (5) to the microcomponent (18) and/or the substrate (1), heating the hot melt type adhesive (5), and placing the microcomponent (18) onto the substrate (1). The hot melt type adhesive (5) is on the contact surfaces between the microcomponent (18) and the substrate (1) during and after gluing.